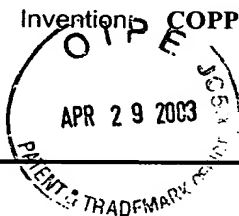


**TRANSMITTAL OF FORMAL DRAWINGS**Docket No.  
FIS920000242 (00750429AA)

In Re Application Of: Burrell et al.

H10  
2822  
6-12-03Serial No.  
09/805,027Filing Date  
03/12/2001Batch No.  
1563Examiner  
M. LewisArt Unit  
2822

Invention: COPPER TO ALUMINUM INTERLAYER INTERCONNECT USING STUD AND VIA LINER

Address to:  
Assistant Commissioner for Patents  
Washington, D.C. 20231

Transmitted herewith are:

2 sheets of formal drawing(s) for this application.

Each sheet of drawing indicates the identifying indicia suggested in 37 CFR Section 1.84(c) on the reverse side of the drawing.

RECEIVED  
JUN 10 2003  
TC 2800 MAIL ROOM

Signature

Marshall M. Curtis  
Reg. No. 33,138  
Whitham, Curtis & Christofferson, P.C.  
11491 Sunset Hills Road, Suite 340  
Reston, VA 20190  
(703) 787-9400

30743

PATENT TRADEMARK OFFICE

Dated: April 29, 2003

I certify that this document and attached formal drawings are being deposited on \_\_\_\_\_ with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Signature of Person Mailing Correspondence

Hand Delivered

Typed or Printed Name of Person Mailing Correspondence